



# HSB1426

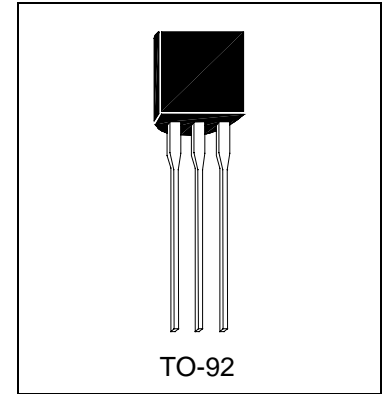
PNP EPITAXIAL PLANAR TRANSISTOR

## Description

DC-DC Converter

## Features

- Low Collector to Emitter Saturation Voltage



## Absolute Maximum Ratings

- Maximum Temperatures  
Storage Temperature ..... -55 ~ +150 °C  
Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
Total Power Dissipation (Ta=25°C) ..... 750 mW
- Maximum Voltages and Currents (Ta=25°C)  
VCBO Collector to Base Voltage ..... -20 V  
VCEO Collector to Emitter Voltage ..... -20 V  
VEBO Emitter to Base Voltage ..... -6 V  
IC Collector Current ..... -3 A

## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-20	-	-	V	IC=-50uA, IE=0
BVCEO	-20	-	-	V	IC=-1mA, IB=0
BVEBO	-6	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-100	nA	VCB=-20V, IE=0
IEBO	-	-	-100	nA	VEB=-5V, IC=0
*VCE(sat)	-	-	-500	mV	IC=-2A, IB=-0.1A
*hFE	82	-	390		VCE=-2V, IC=-100mA
fT	-	240	-	MHz	VCE=-2V, IC=-500mA, f=100MHz
Cob	-	35	-	pF	VCB=-10V, IE=0, f=1MHz

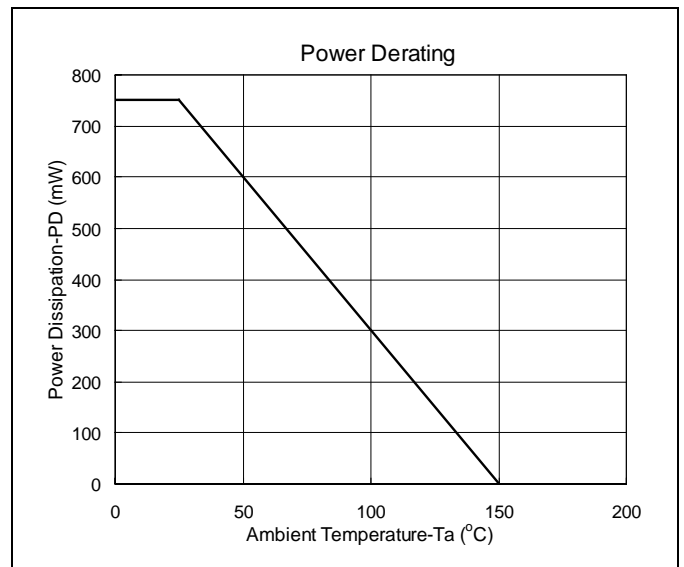
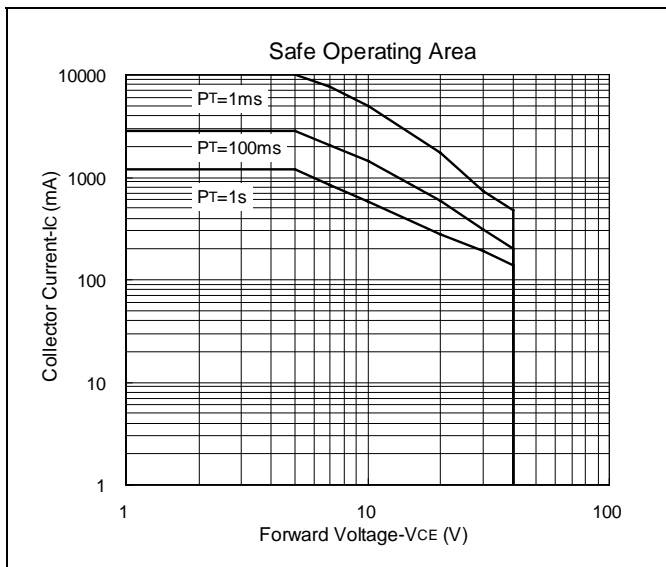
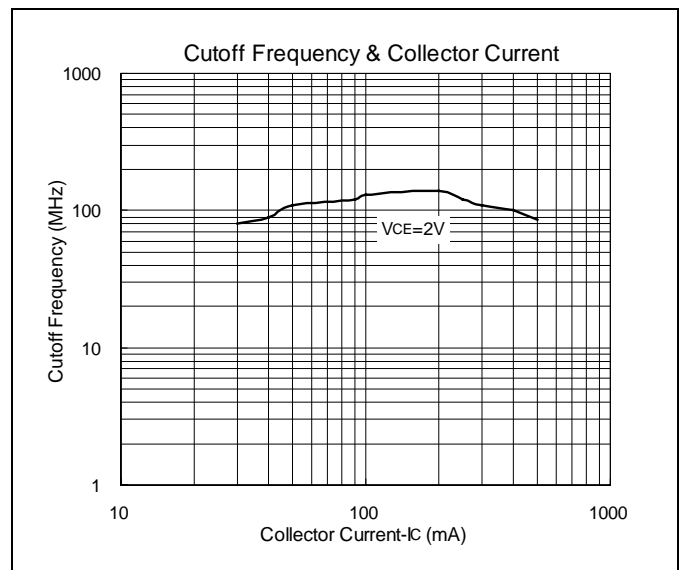
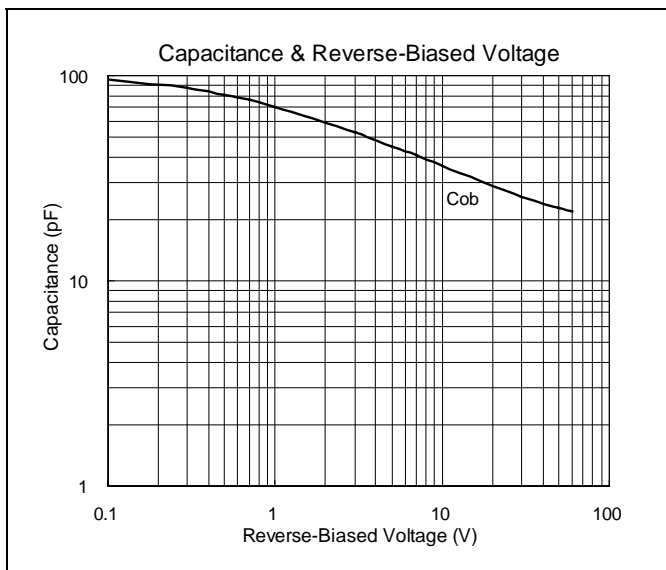
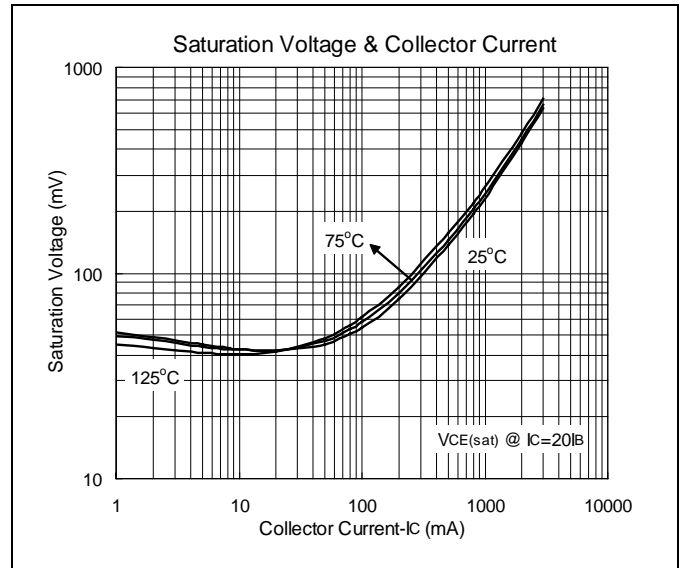
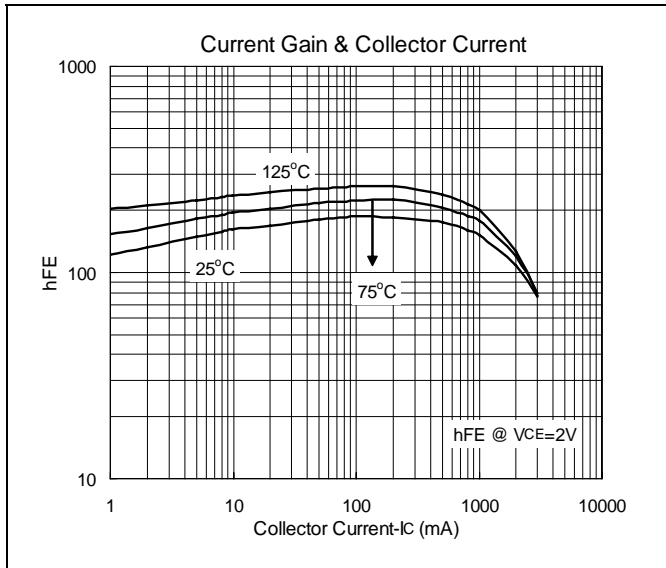
\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

## Classification Of hFE1

Rank	P	Q	R
Range	82-180	120-270	180-390

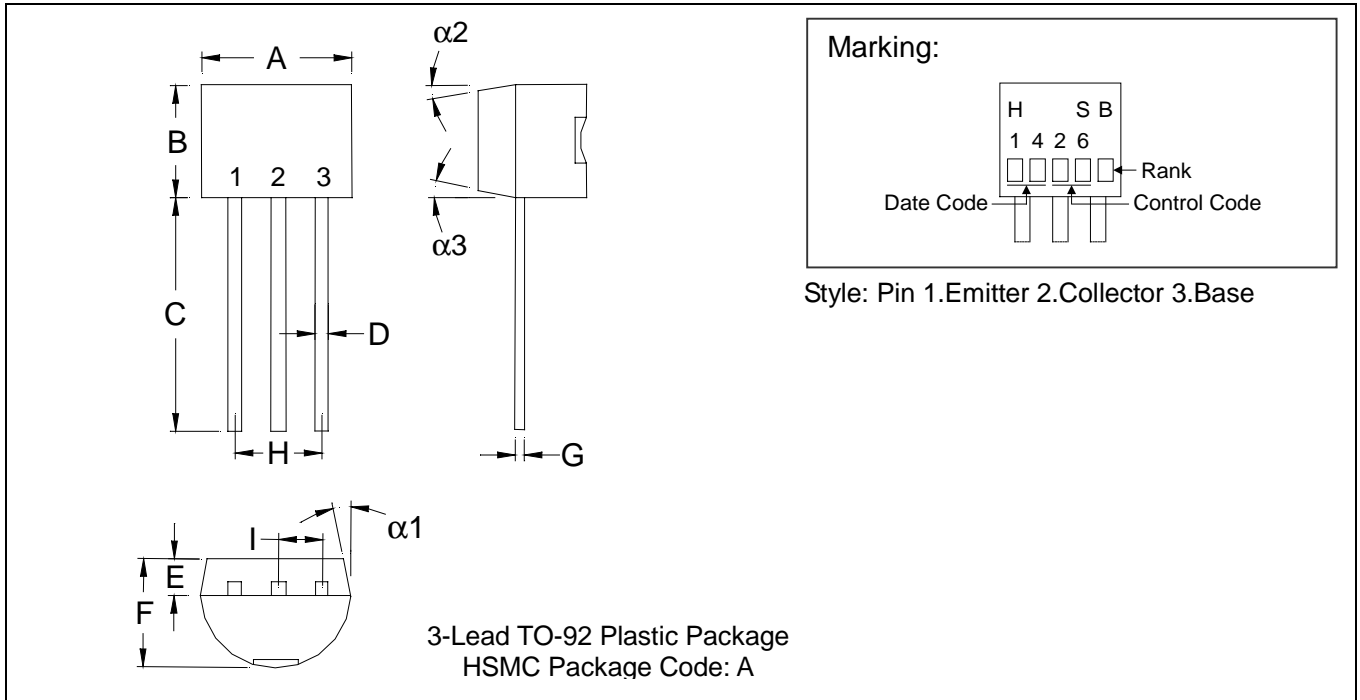


### Characteristics Curve





### TO-92 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

**Notes:** 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.  
 2.Controlling dimension: millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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